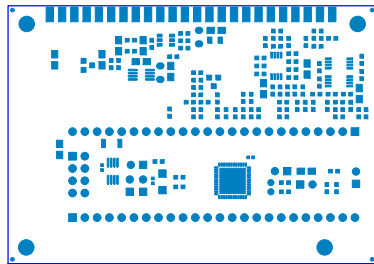
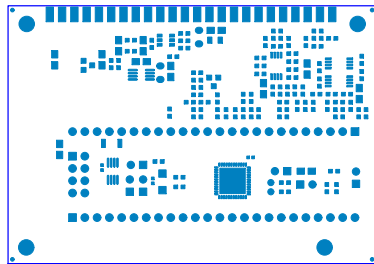


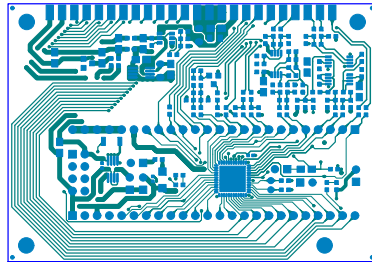
Silkscreen Top



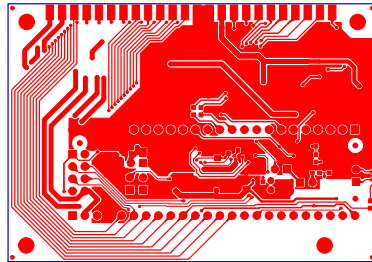
Soldermask Top



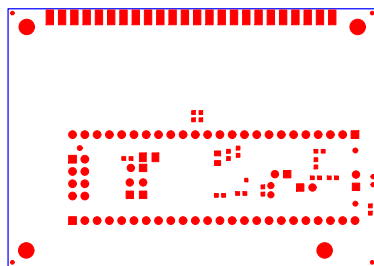
Pastemask Top



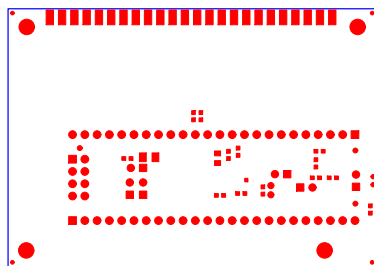
Top Side - Layer 1



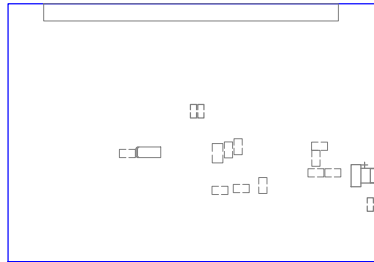
Bottom Side - Layer 2



Bottom Side - Layer 2

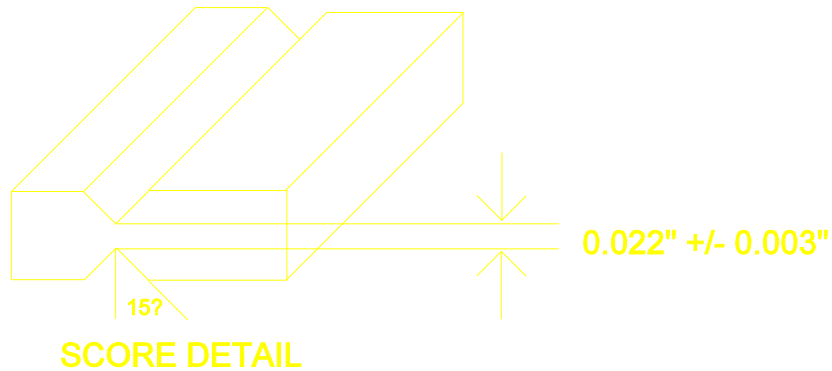


Soldermask Bottom

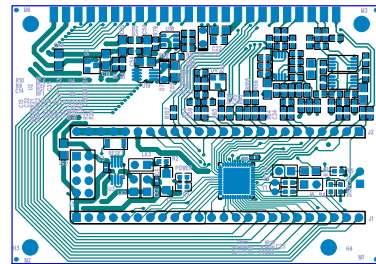


Bottom Side - Layer 2





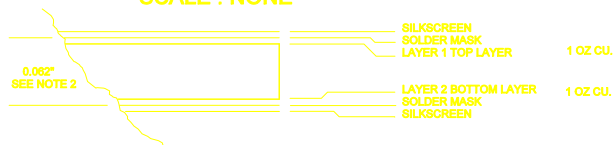
15?



Top Side - Layer 1

## 2 LAYER CONSTRUCTION DETAIL

SCALE : NONE



1. BOARD TO BE FABRICATED PER IPC-6012A, CLASS 2.
2. MATERIAL: POLYCLAD FR-370HR OR EQUIVALENT. OUTER LAYERS 1/2 OZ/SQFT CU INNER LAYERS 1/2 OZ/SQFT CU FINISHED 0.062 (.050 MIN .070 MAX SEE DETAIL). VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
3. PLATING: ADDITIONAL CU PLATING 1 OZ/SQFT MINIMUM PTH BARREL THICKNESS = 0.012" MINIMUM AVERAGE PER IPC-6012A WITH AMENDMENT 1, CLASS 2 REQUIREMENTS WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
4. FINISH: SURFACES TO BE COATED BY ENIG OF 2 TO 10 MICROINCHES OVER A MINIMUM OF 60-200 MICROINCHES OF LOW STRESS NICKEL.
5. SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES.
6. SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
7. ARTWORK: MINIMUM FEATURE SIZE = 0.00492 MINIMUM AIR GAP = 0.00449
8. ALL DIMENSIONS ARE IN INCHES.
9. CONTROLLED IMPEDANCE: BOARD TO BE BUILT TO YIELD CONTROLLED IMPEDANCE OF 50 OHMS +/- 10% ON ALL 0.007", 0.008", 0.0010" LINE WIDTHS
10. DO NOT ADD NON-FUNCTIONAL COPPER THIEVING ON OPEN AREAS OF OUTER LAYERS. THIEVING IS ALLOWED ON INNER LAYERS, UNLESS OTHERWISE SPECIFIED.
11. VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS. METHOD 1 IS PREFERRED.  
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES BOTH SIDES.  
METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION GOLD, APPLY PRIMARY LPI MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THE APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
12. TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
13. REMOVAL OF NON-FUNCTIONAL PADS ON LAYERS 1 AND 4 IS ACCEPTABLE
14. USE IPC-D 356A NETLIST AS SUPPLIED FOR CHECKING.
15. V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE XX +/- .XXX +/- .005	CONTRACT NO.		831 Woburn Street Wilmington, MA 01887 781-637-2424 Fax: 781-637-101		
	APPROVALS	DATE			
	DRAWN Willie Yue	12/25/2013			
MATERIAL SEE NOTES	CHECKED		FABRICATION DRAWING <b>EVAL-CN0352-EB1Z-MCU</b>		
FINISH SEE NOTES	ENGINEERING		SIZE	DWG NO.	REV
	QUALITY		B		A
DO NOT SCALE THIS DRAWING	MANUFACTURING		SCALE	1:1	SHEET 1 OF 1